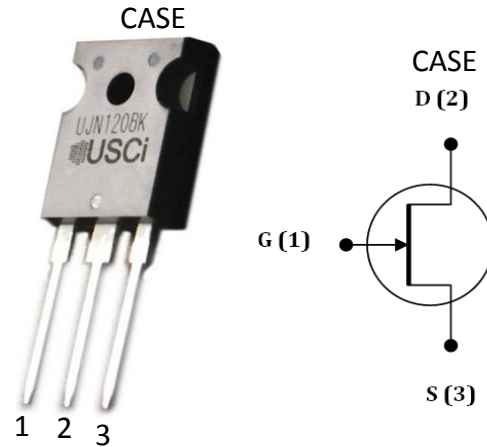


### Features

- Low On-Resistance  $R_{DS(on)max}$  of 0.080Ω
- Voltage controlled
- Maximum operating temperature of 175°C
- Extremely fast switching not dependent on temperature
- Low gate charge
- Low intrinsic capacitance



### Typical Applications

- Over Current Protection Circuits
- DC-AC Inverters
- Switch Mode Power Supplies
- Power Factor Correction Modules
- Motor Drives
- Induction Heating

Part Number	Package	Marking
<b>UJN1208K</b>	<b>TO-247</b>	<b>UJN1208K</b>

### Descriptions

United Silicon Carbide, Inc offers the **xJ series** of high-performance SiC normally-on JFET transistors. This series exhibits ultra-low on resistance ( $R_{DS(ON)}$ ) and gate charge ( $Q_g$ ) allowing for low conduction and switching loss. The device normally-on characteristics with low  $R_{DS(ON)}$  at  $V_{GS} = 0V$  is also ideal for current protection circuits without the need for active control, as well as for cascode operation.

### Absolute Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units
Drain-Source Voltage	$V_{DS}$		1200	V
Gate-Source Voltage	$V_{GS}$	DC	-20 to +3	V
		AC <sup>(1)</sup>	-20 to +20	
Continuous Drain Current	$I_D$	$T_C = 25^\circ C, V_{GS} = 0V$	21	A
Continuous Drain Current	$I_D$	$T_C = 125^\circ C, V_{GS} = 0V$	13	A
Pulsed Drain Current	$I_{DM}$	$T_j = 125^\circ C, V_{GS} = 0V$	41	A
		$T_j = 175^\circ C, V_{GS} = 0V$	35	
Power Dissipation	$P_{tot}$	$T_C = 25^\circ C$	136	W
Operating and Storage Temperature	$T_j, T_{STG}$		-55 to 175	°C
Max Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	$T_L$		250	°C

(1) +20V AC rating applies for turn-on pulses <200ns applied with external  $R_G > 1\Omega$ .

**Electrical Characteristics** ( $T_J = +25^\circ\text{C}$  unless otherwise specified)

**Typical Performance - Static**

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Drain-Source Breakdown Voltage	$BV_{DS}$	$V_{GS} = -20\text{V}, I_D = 1\text{mA}$	1200			V
Total Drain Leakage Current	$I_D$	$V_{DS} = 1200\text{V}, V_{GS} = -20\text{V}, T_J = 25^\circ\text{C}$		40	250	$\mu\text{A}$
		$V_{DS} = 1200\text{V}, V_{GS} = -20\text{V}, T_J = 175^\circ\text{C}$		120	750	
Total Gate Leakage Current	$I_G$	$V_{GS} = -20\text{V}, T_J = 25^\circ\text{C}$		0.3	125	$\mu\text{A}$
		$V_{GS} = -20\text{V}, T_J = 175^\circ\text{C}$		3		
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 2\text{V}, I_F = 20\text{A}, T_J = 25^\circ\text{C}$		67	80	mΩ
		$V_{GS} = 0\text{V}, I_F = 20\text{A}, T_J = 25^\circ\text{C}$		77	95	
		$V_{GS} = 2\text{V}, I_F = 20\text{A}, T_J = 175^\circ\text{C}$		200	240	
		$V_{GS} = 0\text{V}, I_F = 20\text{A}, T_J = 175^\circ\text{C}$		230	285	
Gate Threshold Voltage	$V_{G(th)}$	$V_{DS} = 5\text{V}, I_D = 70\text{mA}$	-10	-7	-4	V
Gate Resistance	$R_G$	$V_{GS} = 0\text{V}, f = 1\text{MHz}$		6		Ω

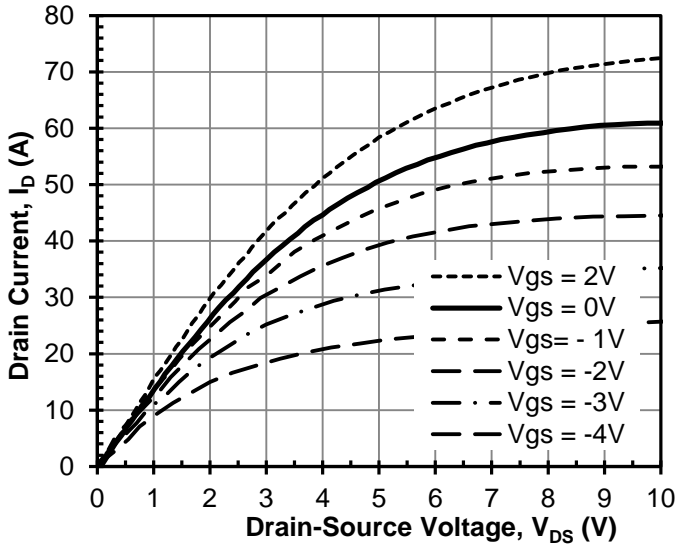
**Typical Performance - Dynamic**

Parameter	symbol	Test Conditions	Value			Units	
			Min	Typ	Max		
Input Capacitance	$C_{iss}$	$V_{DS} = 100V,$ $V_{GS} = -20V,$ $f = 100kHz$		500		pF	
Output Capacitance	$C_{oss}$			94			
Reverse Transfer Capacitance	$C_{rss}$			93			
Effective Output Capacitance, Energy Related	$C_{oss(er)}$	$V_{DS} = 0V$ to 600V, $V_{GS} = -20V$		53		pF	
Total Gate Charge	$Q_G$	$V_{DS}=600V, I_D = 20A,$ $V_{GS}=-15V$ to 2.5V		62		nC	
Gate-Drain Charge	$Q_{GD}$			44			
Gate-Source Charge	$Q_{GS}$			6			
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=600V, I_D=20A,$ Gate Driver =-15V to +5V, $R_{G,EXT} = 2.5\Omega,$ Inductive Load, $T_J = 25^\circ C$		11		ns	
Rise Time	$t_r$			30			
Turn-off Delay Time	$t_{d(off)}$			23			
Fall Time	$t_f$			26			
Turn-on Energy	$E_{ON}$			202			
Turn-off Energy	$E_{OFF}$		210		$\mu J$		
Total Switching Energy	$E_{TOTAL}$		412				
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=600V, I_D=20A,$ Gate Driver =-15V to +5V, $R_{G,EXT} = 2.5\Omega,$ Inductive Load, $T_J = 150^\circ C$		11		ns	
Rise Time	$t_r$			33			
Turn-off Delay Time	$t_{d(off)}$			22			
Fall Time	$t_f$			23			
Turn-on Energy	$E_{ON}$			220			
Turn-off Energy	$E_{OFF}$			174			$\mu J$
Total Switching Energy	$E_{TOTAL}$			394			

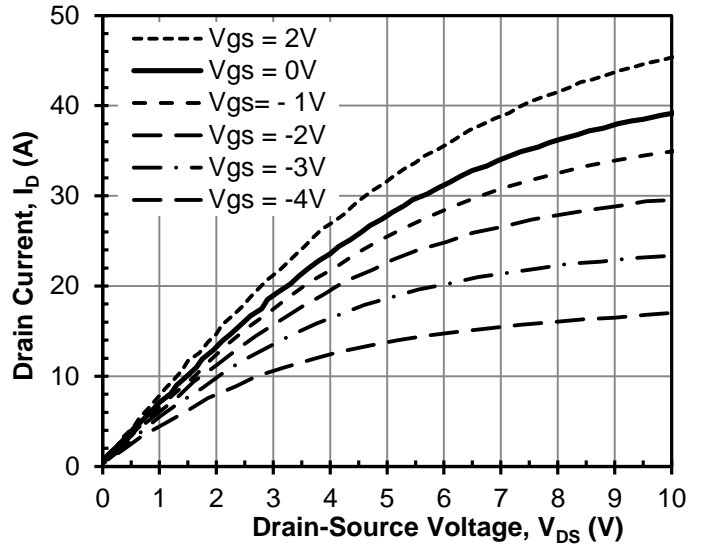
**Thermal characteristics**

Parameter	symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$				1.1	$^\circ C/W$

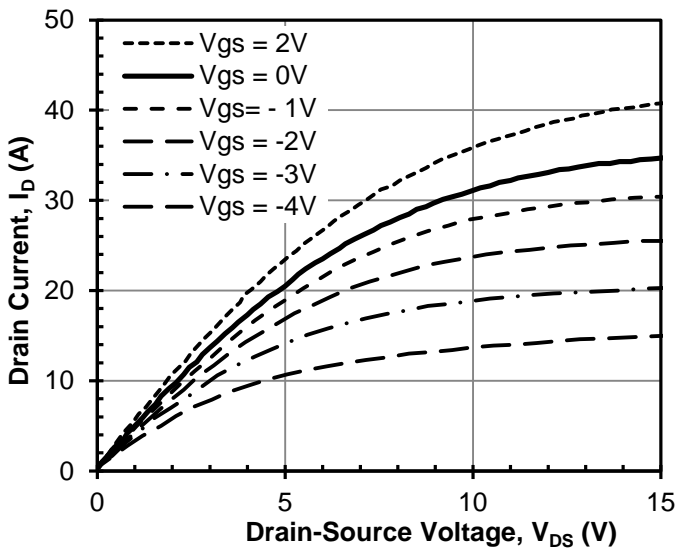
**Typical Performance Diagrams**



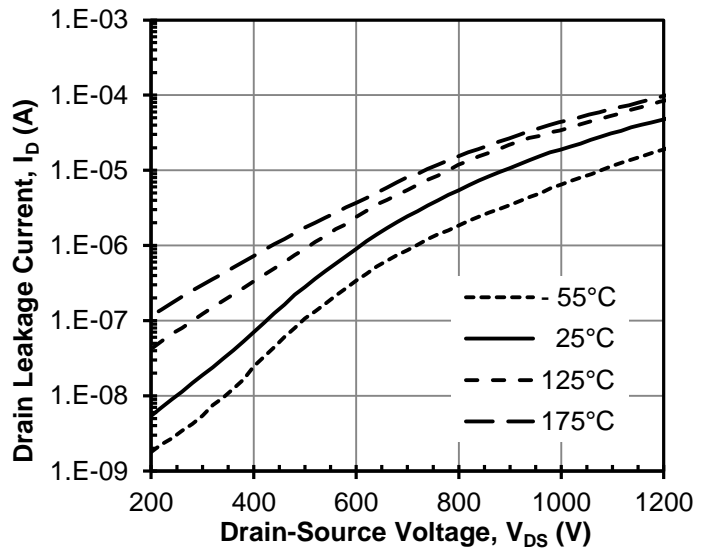
**Figure 1 Typical output characteristics at  $T_j = 25^\circ\text{C}$**



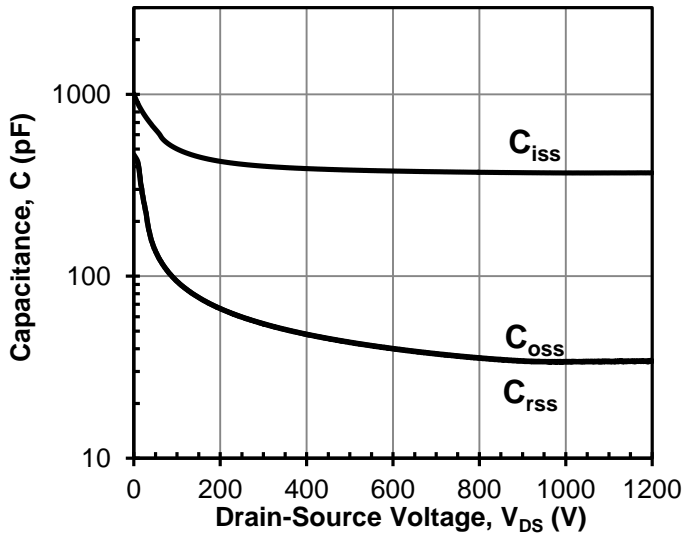
**Figure 2 Typical output characteristics at  $T_j = 125^\circ\text{C}$**



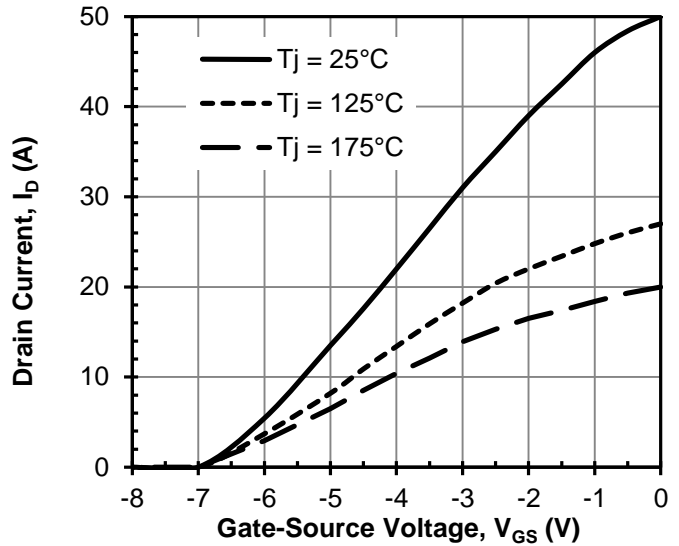
**Figure 3 Typical output characteristics at  $T_j = 175^\circ\text{C}$**



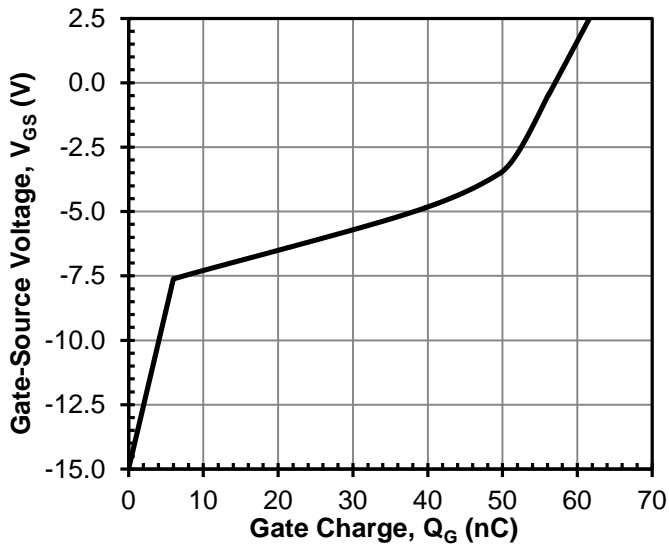
**Figure 4 Typical drain-source leakage at  $V_{GS} = -20\text{V}$**



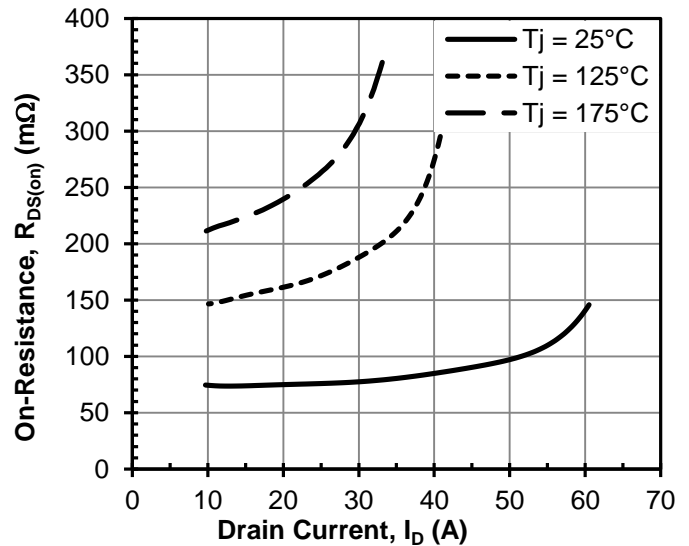
**Figure 5 Typical capacitances at 100kHz and  $V_{GS} = -20V$**



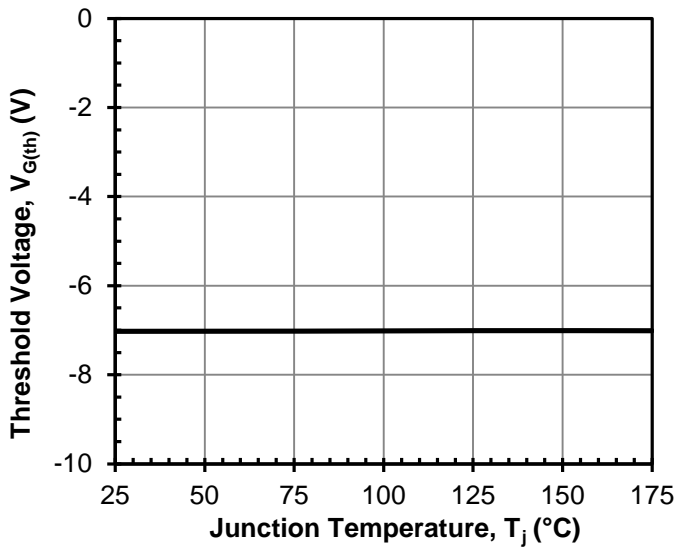
**Figure 6 Typical transfer characteristics at  $V_{DS} = 5V$**



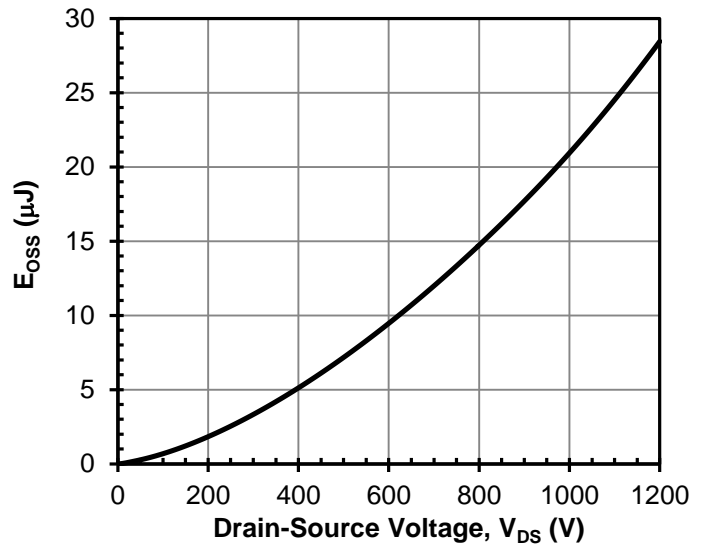
**Figure 7 Typical gate charge at  $V_{DS} = 600V$  and  $I_D = 20A$**



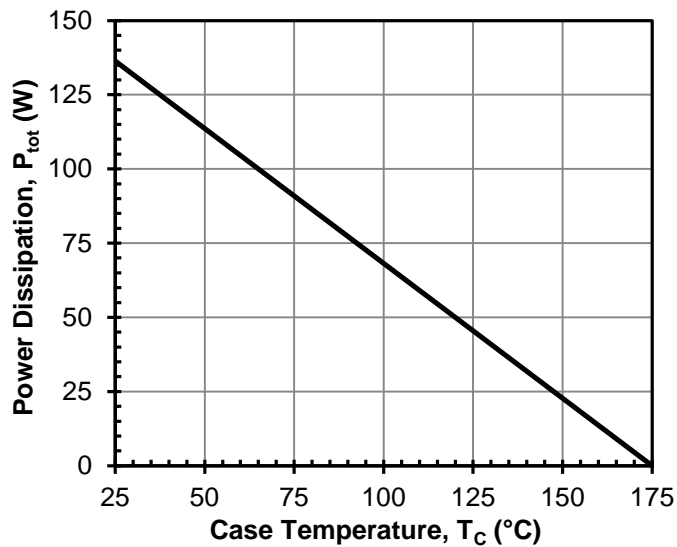
**Figure 8 Typical drain-source on-resistance at  $V_{GS} = 0V$**



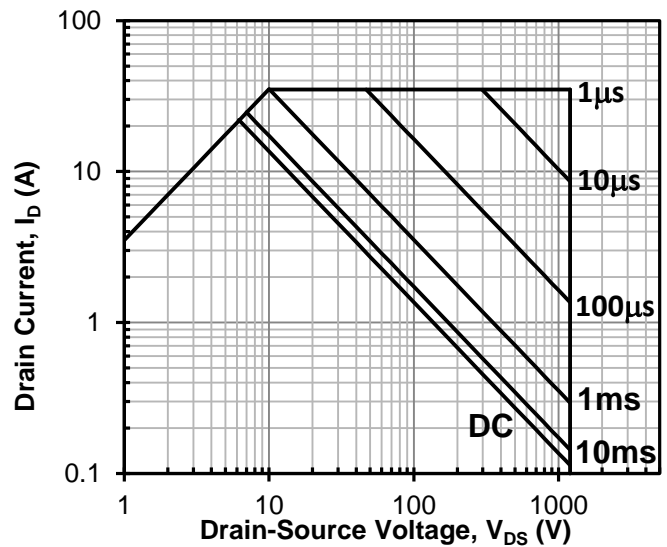
**Figure 9** Threshold voltage vs.  $T_j$   
at  $V_{DS} = 5V$  and  $I_D = 70mA$



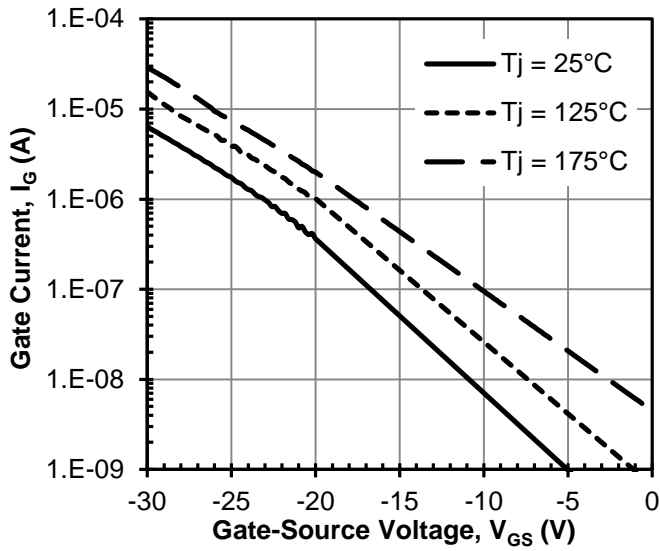
**Figure 10** Typical stored energy in  $C_{oss}$   
at  $V_{GS} = -20V$



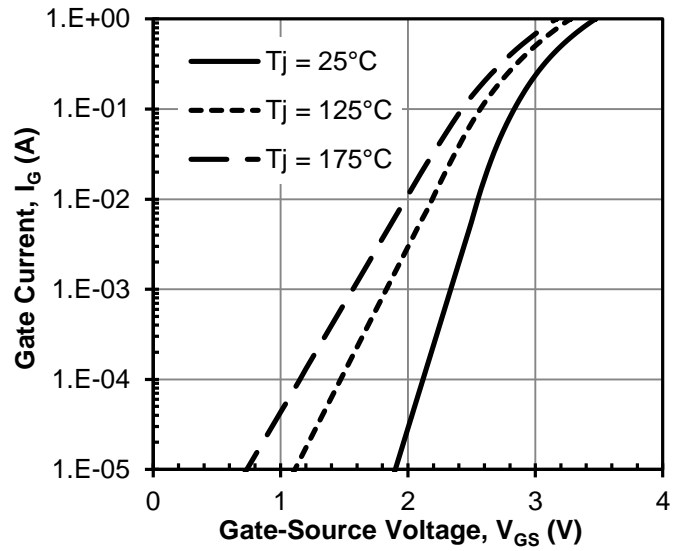
**Figure 11** Total power Dissipation



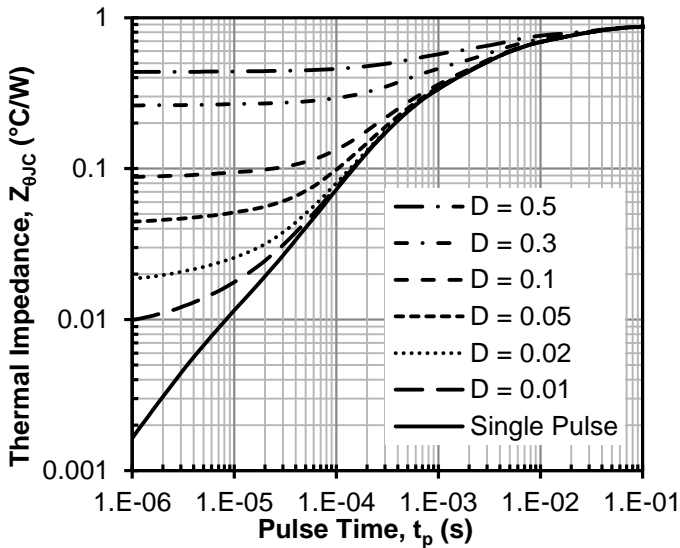
**Figure 12** Safe operation area  
 $T_c = 25^\circ C$ , Parameter  $t_p$



**Figure 13 Typical gate leakage current at  $V_{DS} = 0V$**

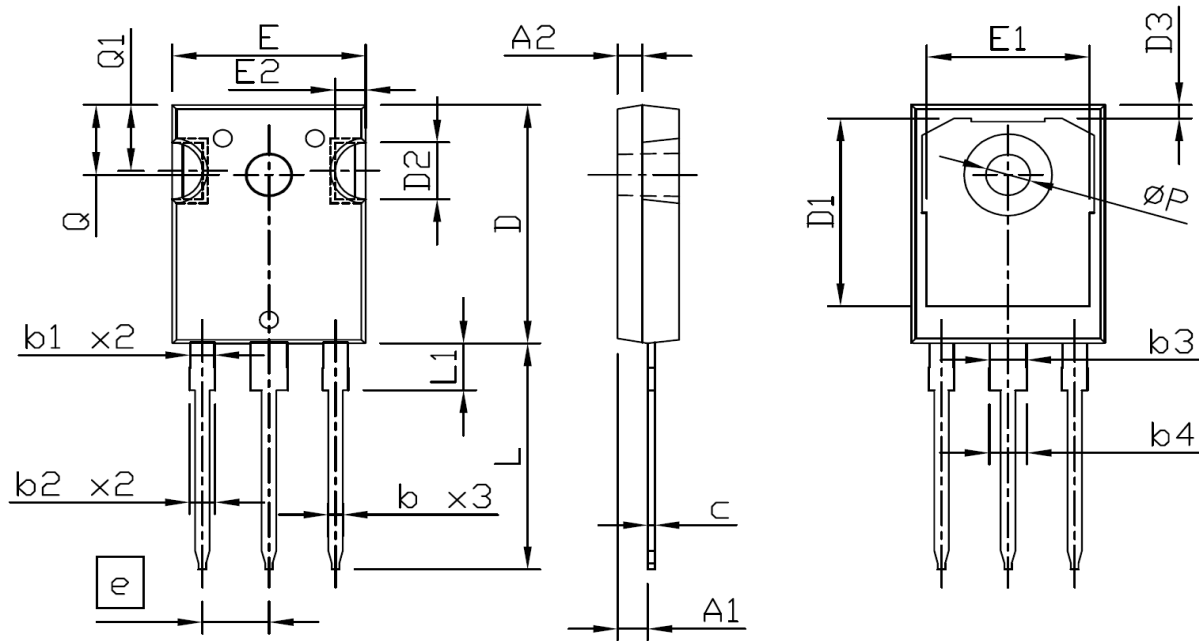


**Figure 14 Typical gate forward current at  $V_{DS} = 0V$**

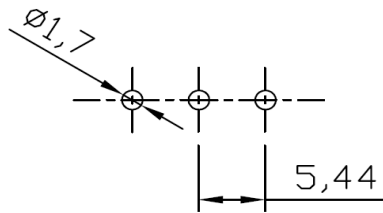


**Figure 15 Typical transient thermal impedance**

**Mechanical Characteristics**



RECOMMENDED LAND PATTERN



UNIT: mm

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.90	5.00	5.10	0.193	0.197	0.201
A1	2.31	2.42	2.52	0.091	0.095	0.099
A2	1.90	2.00	2.10	0.075	0.079	0.083
b	1.16	1.22	1.27	0.046	0.048	0.050
b1	1.96	2.02	2.07	0.078	0.080	0.081
b2	2.00	2.10	2.20	0.079	0.083	0.087
b3	2.96	3.02	3.07	0.117	0.119	0.121
b4	3.00	3.10	3.20	0.118	0.122	0.126
c	0.59	0.62	0.66	0.023	0.024	0.026
D	20.90	21.00	21.10	0.823	0.827	0.831
D1	16.25	16.55	16.85	0.640	0.652	0.663
D2	5.00 TYP			0.197 TYP		
D3	1.05	1.20	1.35	0.041	0.047	0.053
e	5.44 BSC			0.214 BSC		
E	15.70	15.80	15.90	0.618	0.622	0.626
E1	13.06	13.26	13.50	0.514	0.522	0.530
E2	2.50 TYP			0.098 TYP		
L	19.72	19.92	20.12	0.776	0.784	0.792
L1	---	---	4.30	---	---	0.169
Q	6.15 BSC			0.242 BSC		
Q1	5.60	5.80	6.00	0.220	0.228	0.236
ØP	3.55	3.60	3.70	0.140	0.142	0.146

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